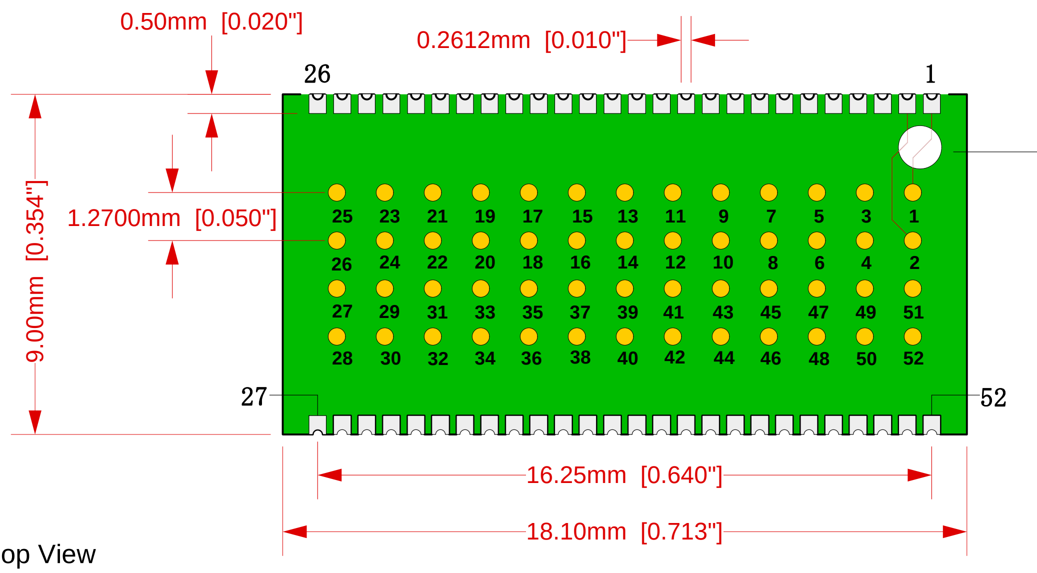
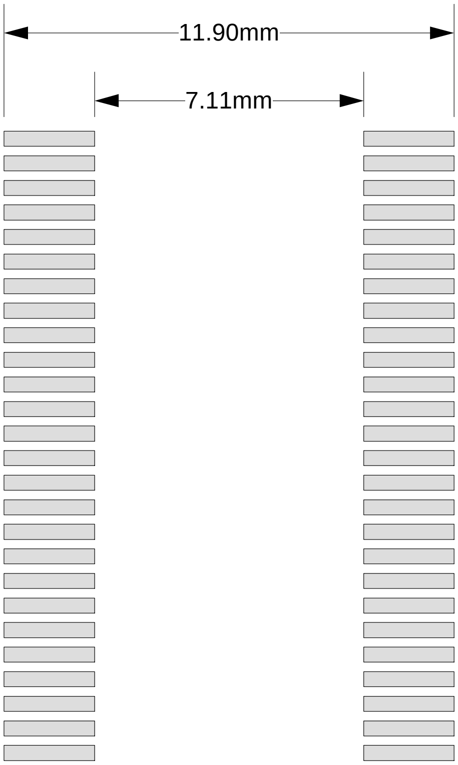
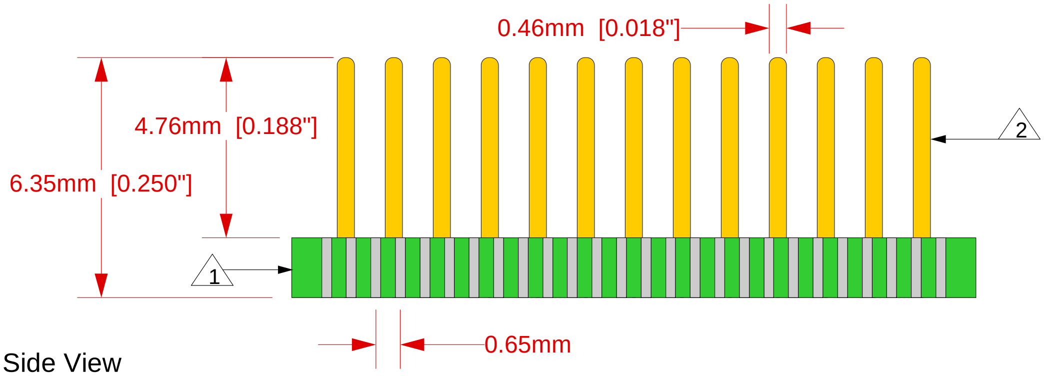


Top View

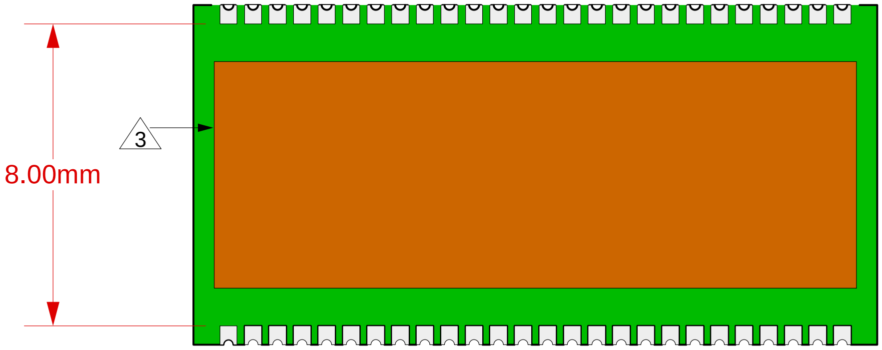
**Note: Pin mapping from side pads to terminal pins is not symmetrical. Foot must solder to target PCB with Pin one of foot aligned to target board Pin 1.**

Compatable target board land dimensions





Side View



Bottom View

1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

3 Kaptop Tape, insulates pins pads from target board

Description: Surface mount foot (SF)
52 position TSOP surface mount leadless foot with 52 position terminal pins.

Tolerances: diameters ±0.03mm [±0.001”], PCB perimeters ±0.13mm [±0.005”], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005”] unless stated otherwise.

| | | | |
|---|---|---|---|
| **SF-SO52B-L-01 Drawing** | Status: Preliminary | Scale: 2:1 | Rev: A |
| <br>Tele: (800) 404-0204<br>www.ironwoodelectronics.com | Drawing: E Smolentseva | | Date: 4/5/11 |
| | File: SF-SO52B-L-01 Dwg | | Modified: |